

MOSFET – P-Channel, QFET®

-60 V, -30 A, 26 mΩ

FQPF47P06, FQPF47P06YDTU

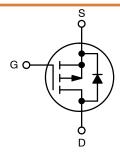
Description

This P-Channel enhancement mode power MOSFET is produced using **onsemi**'s proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on–state resistance, and to provide superior switching performance and high avalanche energy strength. These devices are suitable for switched mode power supplies, audio amplifier, DC motor control, and variable switching power applications.

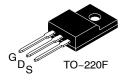
Features

- -30 A, -60 V, $R_{DS(on)} = 26 \text{ m}\Omega$ (Max.) @ $V_{GS} = -10 \text{ V}$, $I_D = -15 \text{ A}$
- Low Gate Charge (Typ. 84 nC)
- Low Crss (Typ. 320 pF)
- 100% Avalanche Tested
- 175°C Maximum Junction Temperature Rating

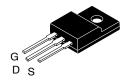
| V _{DSS} | R _{DS(ON)} MAX | I _D MAX | |
|------------------|-------------------------|--------------------|--|
| -60 V | 26 mΩ @ -10 V | -30 A | |



P-Channel MOSFET

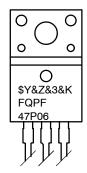


TO-220 Fullpack, 3-Lead / TO-220F-3SG CASE 221AT



TO-220-3LD LF CASE 340BJ

MARKING DIAGRAM



\$Y = onsemi Logo

&Z = Assembly Plant Code &3 = 3-Digit Plant Code

&K = 2-Digits Lot Run Traceability Code

FQPF47P06 = Specific Device Code

ORDERING INFORMATION

| Device | Package | Shipping |
|---------------|-----------------------|-------------------|
| FQPF47P06 | TO-220-3 (Pb-Free) | 1000 Units / Tube |
| FQPF47P06YDTU | TO-220-3 (Pb-Free) | 800 Units / Tube |

ABSOLUTE MAXIMUM RATINGS (T_C = 25°C unless otherwise specified)

| Symbol | Parameter | | FQPF47P06 / FQPF47P06YDTU | U Unit |
|-----------------------------------|---|---------------------------------------|---------------------------|--------|
| V _{DSS} | Drain-Source Voltage | | -60 | V |
| I _D | Drain Current | – Continuous (T _C = 25°C) | -30 | Α |
| | | - Continuous (T _C = 100°C) | -21.2 | Α |
| I _{DM} | Drain Current (Note 1) | - Pulsed | -120 | Α |
| V_{GSS} | Gate-Source Voltage | | + 25 | V |
| E _{AS} | Single Pulsed Avalanche Energy (Note 2) | | 820 | mJ |
| I _{AR} | Avalanche Current (Note 1) | | -30 | Α |
| E _{AR} | Repetitive Avalanche Energy (Note 1) | | 6.2 | mJ |
| dv/dt | Peak Diode Recovery dv/dt (Note 3 | 3) | -7.0 | V/ns |
| P_{D} | Power Dissipation (T _C = 25°C) | | 62 | W |
| | | - Derate above 25°C | 0.41 | W/°C |
| T _J , T _{STG} | Operating and Storage Temperature Range | | −55 to +175 | °C |
| T_L | Maximum Lead Temperature for Soldering Purposes, 1/8" from Case for 5 Seconds | | 300 | °C |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.
1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. L = 1.06 mH, $I_{AS} = -30$ A, $V_{DD} = -25$ V, $R_G = 25$ Ω , Starting $T_J = 25^{\circ}C$
3. $I_{SD} \le -47$ A, di/dt ≤ 300 A/ μ s, $V_{DD} \le BV_{DSS}$, Starting $T_J = 25^{\circ}C$

THERMAL CHARACTERISTICS

| Symbol | Characteristic | | Max | Unit |
|----------------|---|---|------|------|
| $R_{	heta JC}$ | Thermal Resistance, Junction-to-Case | | 2.42 | °C/W |
| $R_{	heta JA}$ | Thermal Resistance, Junction-to-Ambient | - | 62.5 | °C/W |

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

| Symbol | Parameter | Test Condition | Min | Тур | Max | Unit |
|----------------------------------|---|---|------|-------|-------|------|
| OFF CHAR | ACTERISTICS | | | - | • | - |
| BV _{DSS} | Drain-Source Breakdown Voltage | $V_{GS} = 0 \text{ V, } I_D = -250 \mu\text{A}$ | -60 | | _ | V |
| $\Delta BV_{DSS} / \Delta T_{J}$ | Breakdown Voltage Temperature Coefficient | I_D = -250 μ A, Referenced to 25°C | - | -0.06 | - | V/°C |
| I _{DSS} | Zero Gate Voltage Drain Current | V _{DS} = -60 V, V _{GS} = 0 V | - | - | -1 | μΑ |
| | | $V_{DS} = -48 \text{ V}, T_{C} = 150^{\circ}\text{C}$ | - | - | -10 | μΑ |
| I _{GSSF} | Gate-Body Leakage Current, Forward | $V_{GS} = -25 \text{ V}, V_{DS} = 0 \text{ V}$ | - | - | -100 | nA |
| I _{GSSR} | Gate-Body Leakage Current, Reverse | V _{GS} = 25 V, V _{DS} = 0 V | - | - | 100 | nA |
| ON CHARA | ACTERISTICS | | | | | |
| V _{GS(th}) | Gate Threshold Voltage | $V_{DS} = V_{GS}, I_D = -250 \mu A$ | -2.0 | - | -4.0 | V |
| R _{DS(on)} | Static Drain-Source On-Resistance | $V_{GS} = -10 \text{ V}, I_D = -15 \text{ A}$ | - | 0.021 | 0.026 | Ω |
| 9 _{FS} | Forward Transconductance | $V_{DS} = -30 \text{ V}, I_D = -15 \text{ A (Note 4)}$ | - | 19 | - | S |
| OYNAMIC | CHARACTERISTICS | | | - | | |
| C _{iss} | Input Capacitance | $V_{DS} = -25 \text{ V}, V_{GS} = 0 \text{ V}, f = 1.0 \text{ MHz}$ | - | 2800 | 3600 | pF |
| C _{oss} | Output Capacitance | 7 | - | 1300 | 1700 | pF |
| C _{rss} | Reverse Transfer Capacitance | 7 | - | 320 | 420 | pF |
| SWITCHIN | G CHARACTERISTICS | | | - | | |
| t _{d(on)} | Turn-On Delay Time | $V_{DD} = -30 \text{ V}, I_D = -23.5 \text{ A}, R_G = 25 \Omega$ | - | 50 | 110 | ns |
| t _r | Turn-On Rise Time | (Note 4, 5) | - | 450 | 910 | ns |
| t _{d(off)} | Turn-Off Delay Time | 7 | - | 100 | 210 | ns |
| t _f | Turn-Off Fall Time | | - | 195 | 400 | ns |
| Qg | Total Gate Charge | $V_{DS} = -48 \text{ V}, I_D = -47 \text{ A}, V_{GS} = -10 \text{ V}$ | - | 84 | 110 | nC |
| Q _{gs} | Gate-Source Charge | (Note 4, 5) | - | 18 | - | nC |
| Q_{gd} | Gate-Drain Charge | | - | 44 | - | nC |
| DRAIN-SC | URCE DIODE CHARACTERISTICS AND MAX | IMUM RATING | | | | |
| IS | Maximum Continuous Drain-Source Diode Forward Current | | - | - | -30 | Α |
| I _{SM} | Maximum Pulsed Drain-Source Diode Forward Current | | - | - | -120 | Α |
| V_{SD} | Drain-Source Diode Forward Voltage | $V_{GS} = 0 \text{ V}, I_{S} = -30 \text{ A}$ | - | - | -4.0 | V |
| t _{rr} | Reverse Recovery Time | $V_{GS} = 0 \text{ V, } I_{S} = -47 \text{ A,}$ | - | 130 | - | ns |
| Q _{rr} | Reverse Recovery Charge | $dI_F / dt = 100 A/\mu s$ (Note 4) | - | 0.55 | - | μС |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

4. Pulse Test: Pulse width $\leq 300~\mu s$, Duty cycle $\leq 2\%$

^{5.} Essentially independent of operating temperature

TYPICAL CHARACTERISTICS

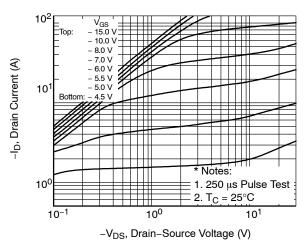


Figure 1. On-Region Characteristics

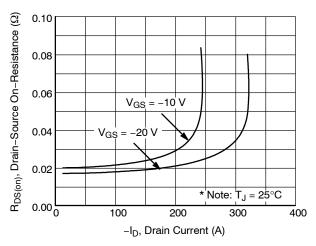


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

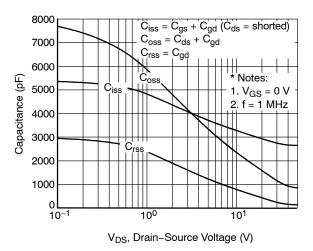


Figure 5. Capacitance Characteristics

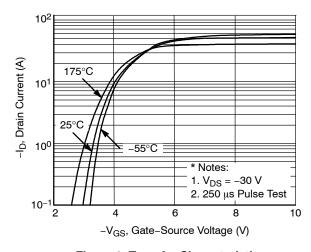


Figure 2. Transfer Characteristics

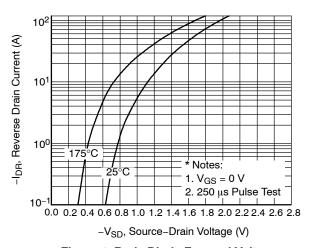


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

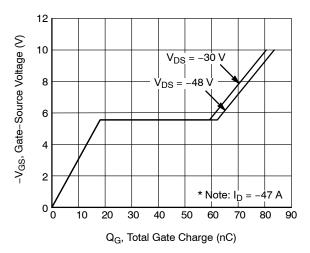


Figure 6. Gate Charge Characteristics

TYPICAL CHARACTERISTICS (Continued)

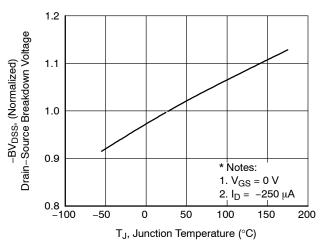


Figure 7. Breakdown Voltage Variation vs. Temperature

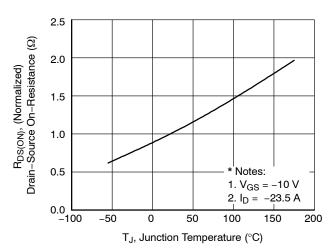


Figure 8. On-Resistance Variation vs. Temperature

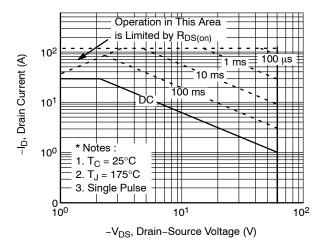


Figure 9. Maximum Safe Operating Area

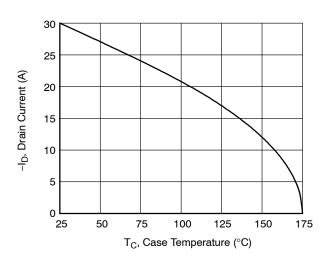


Figure 10. Maximum Drain Current vs. Case Temperature

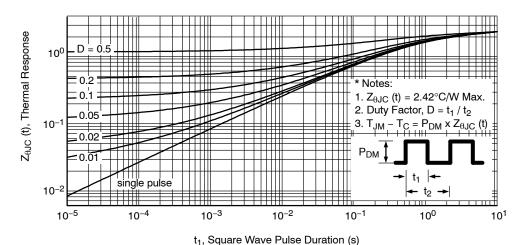


Figure 11. Transient Thermal Response Curve

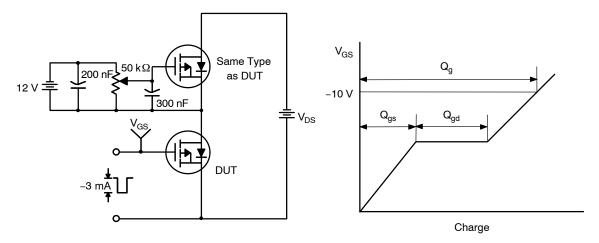


Figure 12. Gate Charge Test Circuit & Waveform

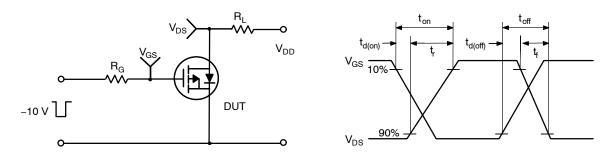


Figure 13. Resistive Switching Test Circuit & Waveforms

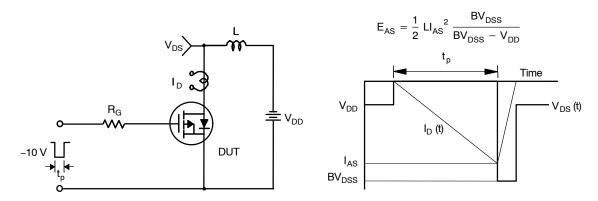
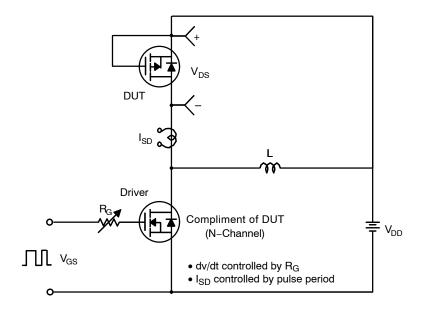


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms



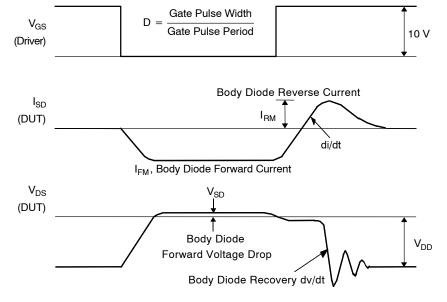
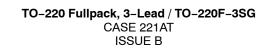
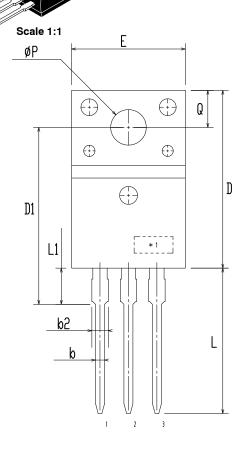
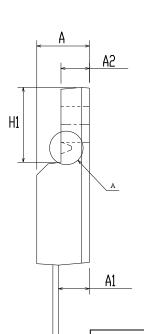


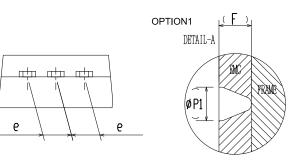
Figure 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms



DATE 19 JAN 2021







| DIM | MILLIMITERS | | | |
|-------|-------------|-------|-------|--|
| ויונע | MIN | NDM | MAX | |
| Α | 4.50 | 4.70 | 4.90 | |
| A1 | 2.56 | 2.76 | 2.96 | |
| A2 | 2.34 | 2.54 | 2.74 | |
| b | 0.70 | 0.80 | 0.90 | |
| b2 | ~ | 2 | 1.47 | |
| С | 0.45 | 0.50 | 0.60 | |
| D | 15.67 | 15.87 | 16.07 | |
| D1 | 15.60 | 15.80 | 16.00 | |
| E | 9.96 | 10.16 | 10.36 | |
| е | 2.34 | 2.54 | 2.74 | |
| F | ~ | 0.84 | 2 | |
| H1 | 6.48 | 6.68 | 6.88 | |
| L | 12.78 | 12.98 | 13.18 | |
| L1 | 3.03 | 3.23 | 3.43 | |
| ØΡ | 2.98 | 3.18 | 3.38 | |
| Ø P1 | ~ | 1.00 | ~ | |
| Q | 3.20 | 3.30 | 3.40 | |

MILLIMITEDS

NOTES:

- A. DIMENSION AND TOLERANCE AS ASME Y14.5-2009
- B. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUCSIONS.

C

C. OPTION 1 - WITH SUPPORT PIN HOLE OPTION 2 - NO SUPPORT PIN HOLE

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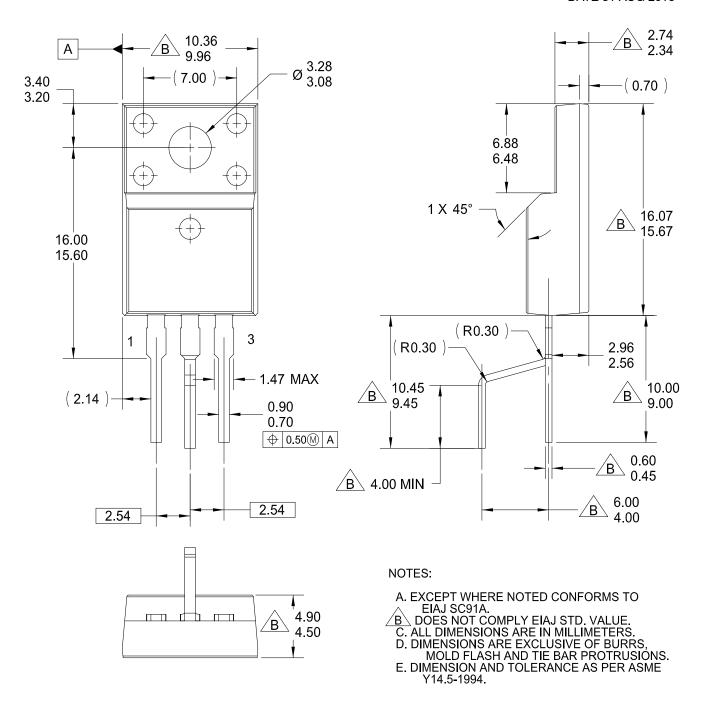
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TO-220-3LD LF CASE 340BJ ISSUE O

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